



Att. Docket No. 10191/1690

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Volker BECKER et al. Confirmation No. 2674

Appl. Serial No. : 09/762,985

Title : DEVICE AND METHOD FOR
ETCHING A SUBSTRATE USING
AN INDUCTIVELY COUPLED PLASMA

Filed : May 8, 2001

TC/A.U. : 1763

Examiner : Luz L. Alejandro Mulero

Docket No. : 10191/1690
Customer No. : 26646

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RESPONSE AFTER A FINAL OFFICE ACTION

S I R:

In response to the Final Office Action mailed on August 23, 2006 (the three-month response date for which has been extended by two months from November 23, 2006 to January 23, 2007 by the accompanying Transmittal and Petition to Extend), please reconsider the above-identified application based on the following:

A Listing of the Claims is provided as a courtesy and begins on page 2 of this paper.

Remarks begin on page 9 of this paper.